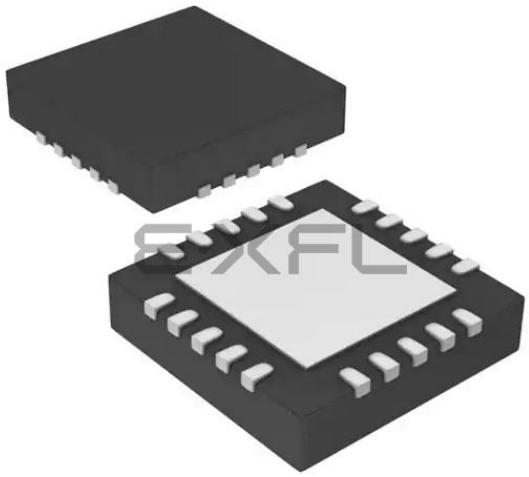

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	17
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 12x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-VFQFN Exposed Pad
Supplier Device Package	20-QFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1509t-i-ml

3.3.1.1 STATUS Register

The STATUS register, shown in Register 3-1, contains:

- the arithmetic status of the ALU
- the Reset status

The STATUS register can be the destination for any instruction, like any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the $\overline{TO}$ and $\overline{PD}$ bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, `CLRF STATUS` will clear the upper three bits and set the Z bit. This leaves the STATUS register as '`000u u1uu`' (where u = unchanged).

It is recommended, therefore, that only `BCF`, `BSF`, `SWAPF` and `MOVWF` instructions are used to alter the STATUS register, because these instructions do not affect any Status bits. For other instructions not affecting any Status bits (Refer to **Section 28.0 "Instruction Set Summary"**).

Note 1: The C and DC bits operate as $\overline{Borrow}$ and $\overline{Digit\ Borrow}$ out bits, respectively, in subtraction.

REGISTER 3-1: STATUS: STATUS REGISTER

U-0	U-0	U-0	R-1/q	R-1/q	R/W-0/u	R/W-0/u	R/W-0/u
—	—	—	$\overline{TO}$	$\overline{PD}$	Z	DC(1)	C(1)
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Value depends on condition

bit 7-5 **Unimplemented:** Read as '0'

bit 4 **$\overline{TO}$:** Time-Out bit
- 1 = After power-up, `CLRWDT` instruction or `SLEEP` instruction
- 0 = A WDT time-out occurred

bit 3 **$\overline{PD}$:** Power-Down bit
- 1 = After power-up or by the `CLRWDT` instruction
- 0 = By execution of the `SLEEP` instruction

bit 2 **Z:** Zero bit
- 1 = The result of an arithmetic or logic operation is zero
- 0 = The result of an arithmetic or logic operation is not zero

bit 1 **DC:** Digit Carry/$\overline{Digit\ Borrow}$ bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions)(1)
- 1 = A carry-out from the 4th low-order bit of the result occurred
- 0 = No carry-out from the 4th low-order bit of the result

bit 0 **C:** Carry/$\overline{Borrow}$ bit(1) (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions)(1)
- 1 = A carry-out from the Most Significant bit of the result occurred
- 0 = No carry-out from the Most Significant bit of the result occurred

Note 1: For $\overline{Borrow}$, the polarity is reversed. A subtraction is executed by adding the two's complement of the second operand. For rotate (`RRF`, `RLF`) instructions, this bit is loaded with either the high-order or low-order bit of the source register.

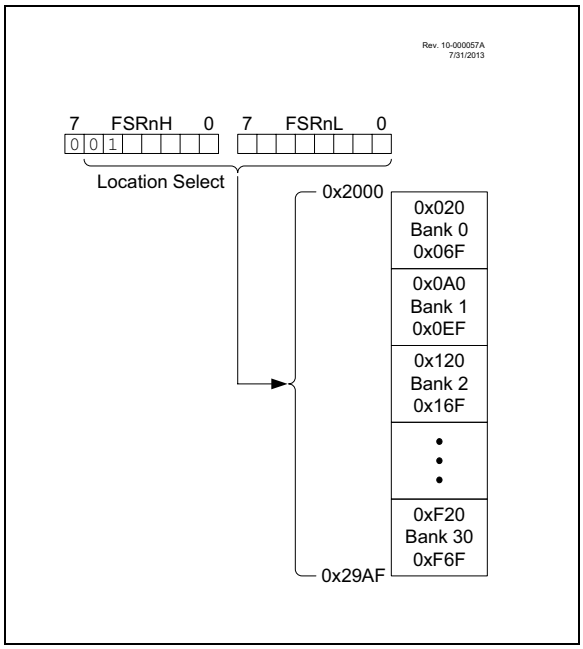
3.6.2 LINEAR DATA MEMORY

The linear data memory is the region from FSR address 0x2000 to FSR address 0x29AF. This region is a virtual region that points back to the 80-byte blocks of GPR memory in all the banks.

Unimplemented memory reads as 0x00. Use of the linear data memory region allows buffers to be larger than 80 bytes because incrementing the FSR beyond one bank will go directly to the GPR memory of the next bank.

The 16 bytes of common memory are not included in the linear data memory region.

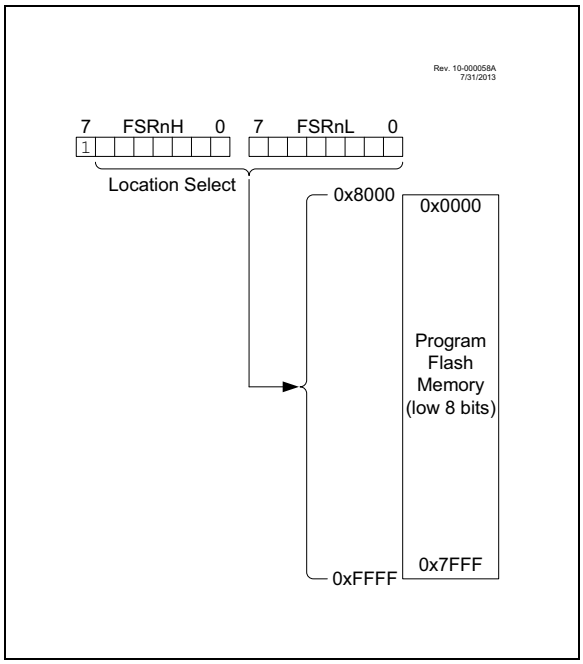
FIGURE 3-10: LINEAR DATA MEMORY MAP



3.6.3 PROGRAM FLASH MEMORY

To make constant data access easier, the entire program Flash memory is mapped to the upper half of the FSR address space. When the MSb of FSRnH is set, the lower 15 bits are the address in program memory which will be accessed through INDF. Only the lower eight bits of each memory location is accessible via INDF. Writing to the program Flash memory cannot be accomplished via the FSR/INDF interface. All instructions that access program Flash memory via the FSR/INDF interface will require one additional instruction cycle to complete.

FIGURE 3-11: PROGRAM FLASH MEMORY MAP



REGISTER 4-1: CONFIG1: CONFIGURATION WORD 1 (CONTINUED)

bit 2-0 **FOSC<2:0>:** Oscillator Selection bits
111 = ECH:External clock, High-Power mode: on CLKIN pin
110 = ECM: External clock, Medium Power mode: on CLKIN pin
101 = ECL: External clock, Low-Power mode: on CLKIN pin
100 = INTOSC oscillator: I/O function on CLKIN pin
011 = EXTRC oscillator: External RC circuit connected to CLKIN pin
010 = HS oscillator: High-speed crystal/resonator connected between OSC1 and OSC2 pins
001 = XT oscillator: Crystal/resonator connected between OSC1 and OSC2 pins
000 = LP oscillator: Low-power crystal connected between OSC1 and OSC2 pins

Note 1: When FSCM is enabled, Two-Speed Start-up will be automatically enabled, regardless of the IESO bit value.
2: Enabling Brown-out Reset does not automatically enable Power-up Timer.
3: Once enabled, code-protect can only be disabled by bulk erasing the device.

5.3.5 CLOCK SWITCHING BEFORE SLEEP

When clock switching from an old clock to a new clock is requested just prior to entering Sleep mode, it is necessary to confirm that the switch is complete before the SLEEP instruction is executed. Failure to do so may result in an incomplete switch and consequential loss of the system clock altogether. Clock switching is confirmed by monitoring the clock status bits in the OSCSTAT register. Switch confirmation can be accomplished by sensing that the ready bit for the new clock is set or the ready bit for the old clock is cleared. For example, when switching between the internal oscillator with the PLL and the internal oscillator without the PLL, monitor the PLLR bit. When PLLR is set, the switch to 32 MHz operation is complete. Conversely, when PPLR is cleared, the switch from 32 MHz operation to the selected internal clock is complete.

5.4 Two-Speed Clock Start-up Mode

Two-Speed Start-up mode provides additional power savings by minimizing the latency between external oscillator start-up and code execution. In applications that make heavy use of the Sleep mode, Two-Speed Start-up will remove the external oscillator start-up time from the time spent awake and can reduce the overall power consumption of the device. This mode allows the application to wake-up from Sleep, perform a few instructions using the INTOSC internal oscillator block as the clock source and go back to Sleep without waiting for the external oscillator to become stable.

Two-Speed Start-up provides benefits when the oscillator module is configured for LP, XT, or HS modes. The Oscillator Start-up Timer (OST) is enabled for these modes and must count 1024 oscillations before the oscillator can be used as the system clock source.

If the oscillator module is configured for any mode other than LP, XT or HS mode, then Two-Speed Start-up is disabled. This is because the external clock oscillator does not require any stabilization time after POR or an exit from Sleep.

If the OST count reaches 1024 before the device enters Sleep mode, the OSTS bit of the OSCSTAT register is set and program execution switches to the external oscillator. However, the system may never operate from the external oscillator if the time spent awake is very short.

Note:	Executing a SLEEP instruction will abort the oscillator start-up time and will cause the OSTS bit of the OSCSTAT register to remain clear.

REGISTER 10-6: PMCON2: PROGRAM MEMORY CONTROL 2 REGISTER

W-0/0	W-0/0	W-0/0	W-0/0	W-0/0	W-0/0	W-0/0	W-0/0
Program Memory Control Register 2							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
S = Bit can only be set	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **Flash Memory Unlock Pattern bits**

To unlock writes, a 55h must be written first, followed by an AAh, before setting the WR bit of the PMCON1 register. The value written to this register is used to unlock the writes. There are specific timing requirements on these writes.

TABLE 10-3: SUMMARY OF REGISTERS ASSOCIATED WITH FLASH PROGRAM MEMORY

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	75
PMCON1	—(1)	CFGS	LWLO	FREE	WRERR	WREN	WR	RD	104
PMCON2	Program Memory Control Register 2								105
PMADRL	PMADRL<7:0>								103
PMADRH	—(1)	PMADRH<6:0>							103
PMDATL	PMDATL<7:0>								103
PMDATH	—	—	PMDATH<5:0>						103

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by Flash program memory.
Note 1: Unimplemented, read as '1'.

TABLE 10-4: SUMMARY OF CONFIGURATION WORD WITH RESETS

Name	Bits	Bit -/7	Bit -/6	Bit 13/5	Bit 12/4	Bit 11/3	Bit 10/2	Bit 9/1	Bit 8/0	Register on Page
CONFIG1	13:8	—	—	FCMEN	IESO	$\overline{\text{CLKOUTEN}}$	BOREN<1:0>		—	41
	7:0	$\overline{\text{CP}}$	MCLRE	$\overline{\text{PWRTE}}$	WDTE<1:0>		FOSC<2:0>			
CONFIG2	13:8	—	—	LVP	—	$\overline{\text{LPBOR}}$	BORV	STVREN	—	43
	7:0	—	—	—	—	—	—	WRT<1:0>		

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by Resets.

18.1.3 SOFTWARE PROGRAMMABLE PRESCALER

A software programmable prescaler is available for exclusive use with Timer0. The prescaler is enabled by clearing the PSA bit of the OPTION_REG register.

Note:	The Watchdog Timer (WDT) uses its own independent prescaler.

There are eight prescaler options for the Timer0 module ranging from 1:2 to 1:256. The prescale values are selectable via the PS<2:0> bits of the OPTION_REG register. In order to have a 1:1 prescaler value for the Timer0 module, the prescaler must be disabled by setting the PSA bit of the OPTION_REG register.

The prescaler is not readable or writable. All instructions writing to the TMR0 register will clear the prescaler.

18.1.4 TIMER0 INTERRUPT

Timer0 will generate an interrupt when the TMR0 register overflows from FFh to 00h. The TMR0IF interrupt flag bit of the INTCON register is set every time the TMR0 register overflows, regardless of whether or not the Timer0 interrupt is enabled. The TMR0IF bit can only be cleared in software. The Timer0 interrupt enable is the TMR0IE bit of the INTCON register.

Note:	The Timer0 interrupt cannot wake the processor from Sleep since the timer is frozen during Sleep.

18.1.5 8-BIT COUNTER MODE SYNCHRONIZATION

When in 8-Bit Counter mode, the incrementing edge on the T0CKI pin must be synchronized to the instruction clock. Synchronization can be accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the instruction clock. The high and low periods of the external clocking source must meet the timing requirements as shown in **Section 29.0 "Electrical Specifications"**.

18.1.6 OPERATION DURING SLEEP

Timer0 cannot operate while the processor is in Sleep mode. The contents of the TMR0 register will remain unchanged while the processor is in Sleep mode.

21.5.8 GENERAL CALL ADDRESS SUPPORT

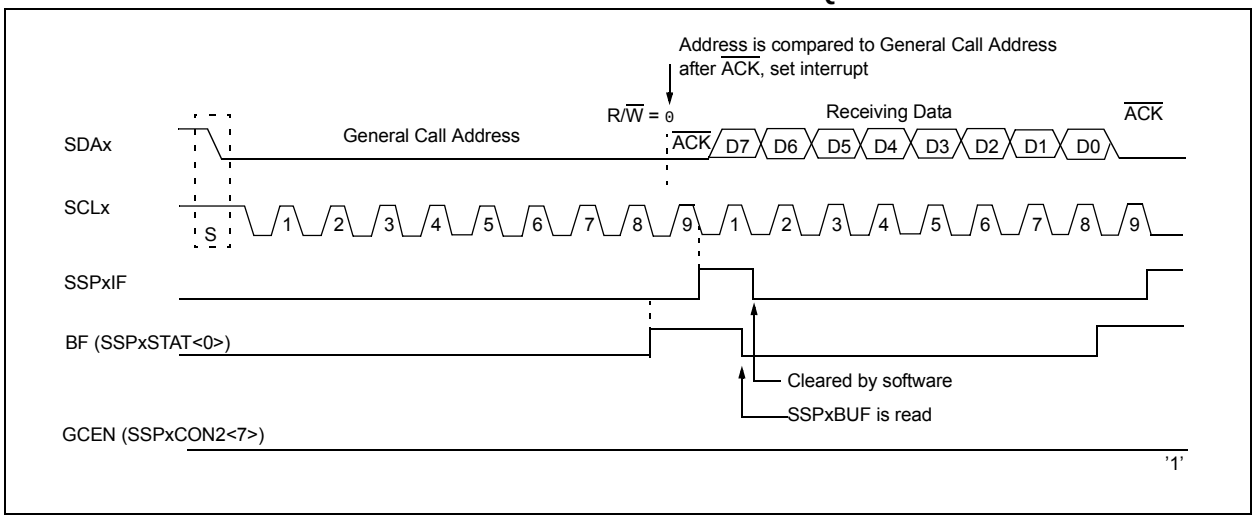
The addressing procedure for the I^2C bus is such that the first byte after the Start condition usually determines which device will be the slave addressed by the master device. The exception is the general call address which can address all devices. When this address is used, all devices should, in theory, respond with an acknowledge.

The general call address is a reserved address in the I^2C protocol, defined as address 0x00. When the GCEN bit of the SSPxCON2 register is set, the slave module will automatically $\overline{ACK}$ the reception of this address regardless of the value stored in SSPxADD. After the slave clocks in an address of all zeros with the R/$\overline{W}$ bit clear, an interrupt is generated and slave software can read SSPxBUF and respond. Figure 21-24 shows a General Call reception sequence.

In 10-bit Address mode, the UA bit will not be set on the reception of the general call address. The slave will prepare to receive the second byte as data, just as it would in 7-bit mode.

If the AHEN bit of the SSPxCON3 register is set, just as with any other address reception, the slave hardware will stretch the clock after the eighth falling edge of SCLx. The slave must then set its ACKDT value and release the clock with communication progressing as it would normally.

FIGURE 21-24: SLAVE MODE GENERAL CALL ADDRESS SEQUENCE



21.5.9 SSPx MASK REGISTER

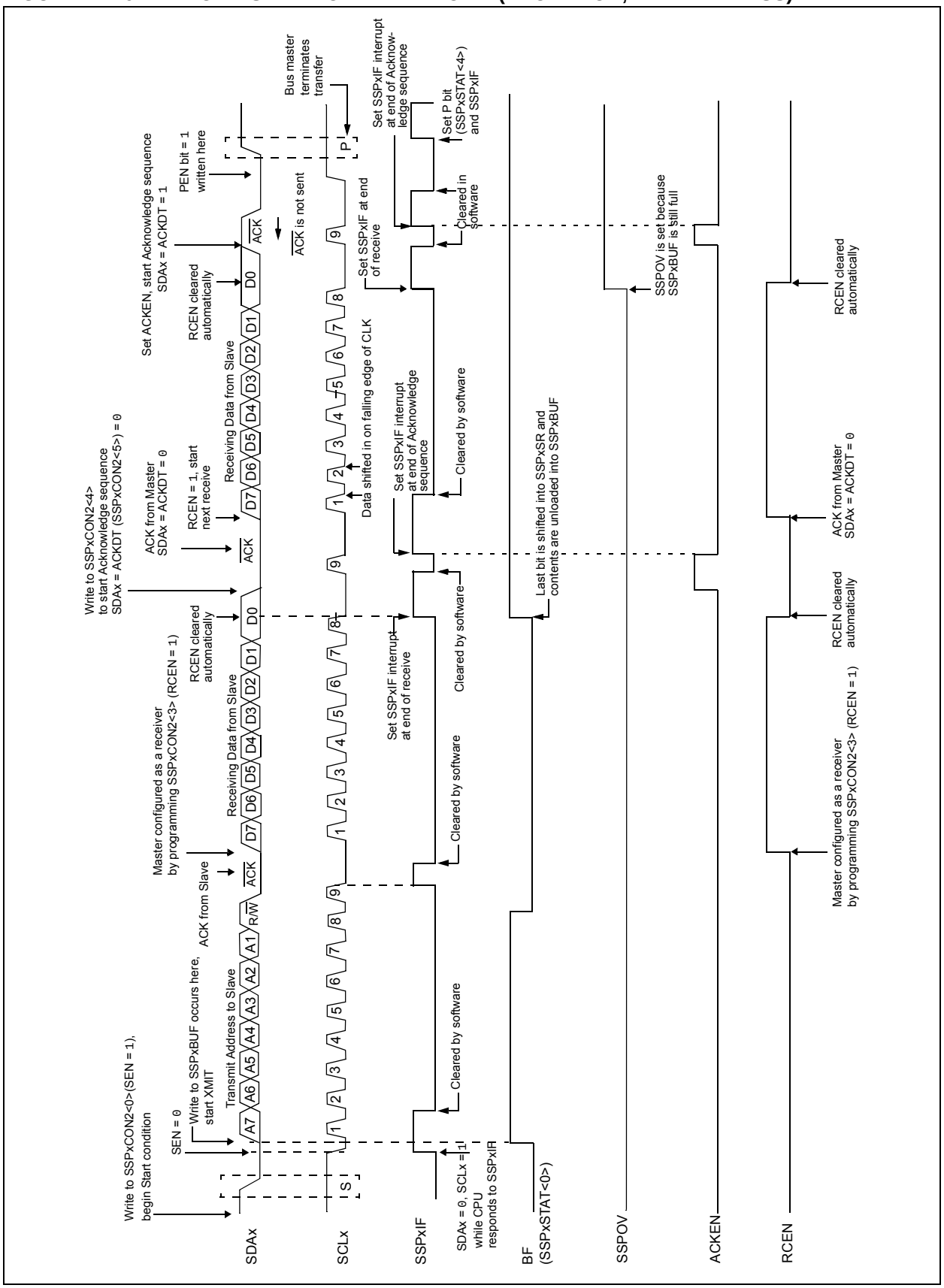
An SSPx Mask (SSPxMSK) register (Register 21-5) is available in I^2C Slave mode as a mask for the value held in the SSPxSR register during an address comparison operation. A zero ('0') bit in the SSPxMSK register has the effect of making the corresponding bit of the received address a "don't care".

This register is reset to all '1's upon any Reset condition and, therefore, has no effect on standard SSPx operation until written with a mask value.

The SSPx Mask register is active during:

- 7-bit Address mode: address compare of A<7:1>.
- 10-bit Address mode: address compare of A<7:0> only. The SSPx mask has no effect during the reception of the first (high) byte of the address.

FIGURE 21-29: I²C MASTER MODE WAVEFORM (RECEPTION, 7-BIT ADDRESS)



21.6.13.1 Bus Collision During a Start Condition

During a Start condition, a bus collision occurs if:

a) SDA or SCL are sampled low at the beginning of the Start condition (Figure 21-33).

b) SCL is sampled low before SDAx is asserted low (Figure 21-34).

During a Start condition, both the SDAx and the SCL pins are monitored.

If the SDA pin is already low, or the SCL pin is already low, then all of the following occur:

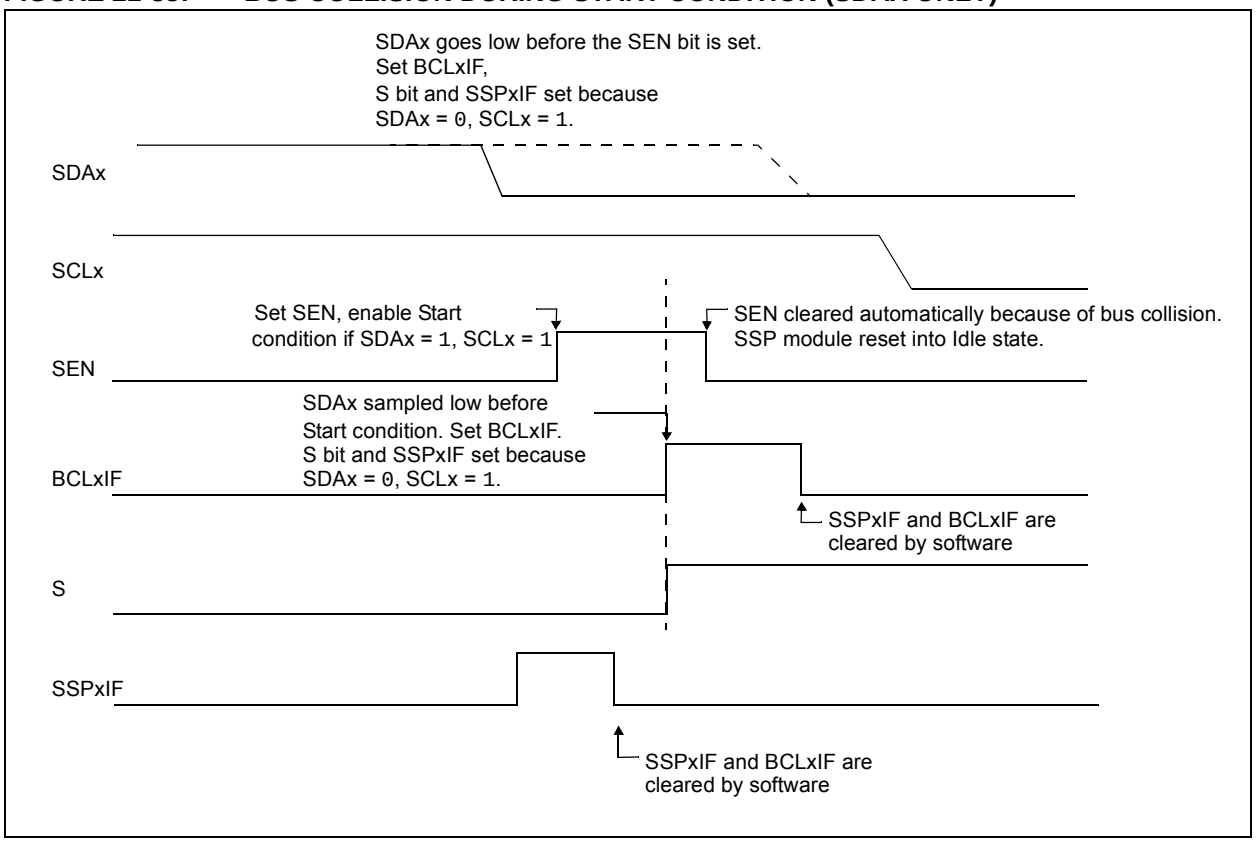
- the Start condition is aborted,
- the BCL1IF flag is set and
- the MSSP module is reset to its Idle state (Figure 21-33).

The Start condition begins with the SDAx and SCLx pins deasserted. When the SDAx pin is sampled high, the Baud Rate Generator is loaded and counts down. If the SCLx pin is sampled low while SDAx is high, a bus collision occurs because it is assumed that another master is attempting to drive a data '1' during the Start condition.

If the SDAx pin is sampled low during this count, the BRG is reset and the SDAx line is asserted early (Figure 21-35). If, however, a '1' is sampled on the SDA pin, the SDA pin is asserted low at the end of the BRG count. The Baud Rate Generator is then reloaded and counts down to zero; if the SCL pin is sampled as '0' during this time, a bus collision does not occur. At the end of the BRG count, the SCL pin is asserted low.

Note:	The reason that bus collision is not a factor during a Start condition is that no two bus masters can assert a Start condition at the exact same time. Therefore, one master will always assert SDAx before the other. This condition does not cause a bus collision because the two masters must be allowed to arbitrate the first address following the Start condition. If the address is the same, arbitration must be allowed to continue into the data portion, Repeated Start or Stop conditions.

FIGURE 21-33: BUS COLLISION DURING START CONDITION (SDAX ONLY)



REGISTER 24-8: CLCxGLS3: GATE 4 LOGIC SELECT REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
LCxG4D4T	LCxG4D4N	LCxG4D3T	LCxG4D3N	LCxG4D2T	LCxG4D2N	LCxG4D1T	LCxG4D1N
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **LCxG4D4T:** Gate 4 Data 4 True (non-inverted) bit
1 = lcxd4T is gated into lcxg4
0 = lcxd4T is not gated into lcxg4

bit 6 **LCxG4D4N:** Gate 4 Data 4 Negated (inverted) bit
1 = lcxd4N is gated into lcxg4
0 = lcxd4N is not gated into lcxg4

bit 5 **LCxG4D3T:** Gate 4 Data 3 True (non-inverted) bit
1 = lcxd3T is gated into lcxg4
0 = lcxd3T is not gated into lcxg4

bit 4 **LCxG4D3N:** Gate 4 Data 3 Negated (inverted) bit
1 = lcxd3N is gated into lcxg4
0 = lcxd3N is not gated into lcxg4

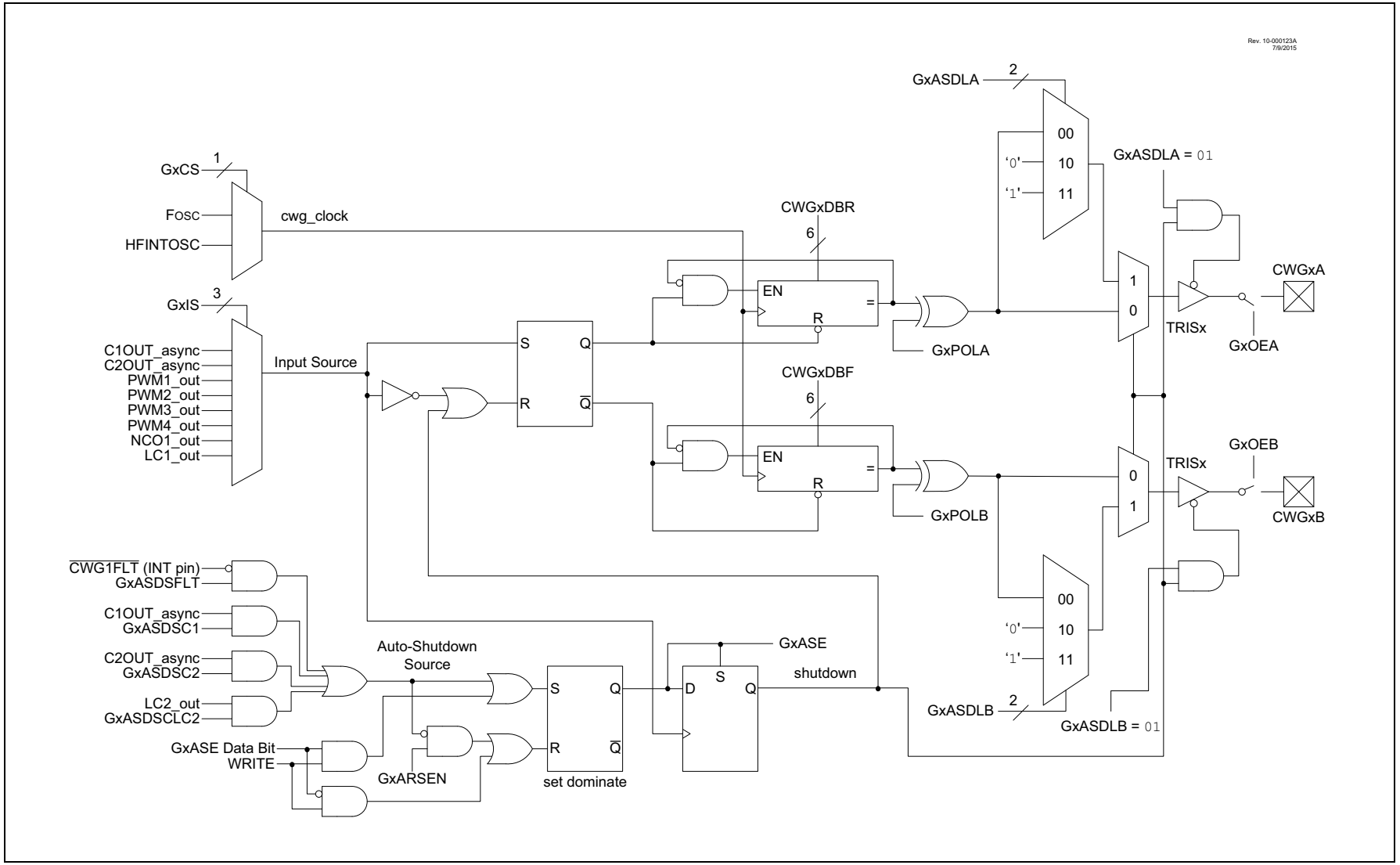
bit 3 **LCxG4D2T:** Gate 4 Data 2 True (non-inverted) bit
1 = lcxd2T is gated into lcxg4
0 = lcxd2T is not gated into lcxg4

bit 2 **LCxG4D2N:** Gate 4 Data 2 Negated (inverted) bit
1 = lcxd2N is gated into lcxg4
0 = lcxd2N is not gated into lcxg4

bit 1 **LCxG4D1T:** Gate 4 Data 1 True (non-inverted) bit
1 = lcxd1T is gated into lcxg4
0 = lcxd1T is not gated into lcxg4

bit 0 **LCxG4D1N:** Gate 4 Data 1 Negated (inverted) bit
1 = lcxd1N is gated into lcxg4
0 = lcxd1N is not gated into lcxg4

FIGURE 26-1: SIMPLIFIED CWG BLOCK DIAGRAM



REGISTER 26-2: CWGxCON1: CWG CONTROL REGISTER 1

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	U-0	R/W-0/0	R/W-0/0	R/W-0/0
GxASDLB<1:0>		GxASDLA<1:0>		—	GxIS<2:0>		
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	q = Value depends on condition

bit 7-6 **GxASDLB<1:0>:** CWGx Shutdown State for CWGxB
When an auto shutdown event is present (GxASE = 1):
11 = CWGxB pin is driven to ‘1’, regardless of the setting of the GxPOLB bit.
10 = CWGxB pin is driven to ‘0’, regardless of the setting of the GxPOLB bit.
01 = CWGxB pin is tri-stated
00 = CWGxB pin is driven to its inactive state after the selected dead-band interval. GxPOLB still will control the polarity of the output.

bit 5-4 **GxASDLA<1:0>:** CWGx Shutdown State for CWGxA
When an auto shutdown event is present (GxASE = 1):
11 = CWGxA pin is driven to ‘1’, regardless of the setting of the GxPOLA bit.
10 = CWGxA pin is driven to ‘0’, regardless of the setting of the GxPOLA bit.
01 = CWGxA pin is tri-stated
00 = CWGxA pin is driven to its inactive state after the selected dead-band interval. GxPOLA still will control the polarity of the output.

bit 3 **Unimplemented:** Read as ‘0’

bit 2-0 **GxIS<2:0>:** CWGx Input Source Select bits
111 = CLC1 – LC1_out
110 = NCO1 – NCO1_out
101 = PWM4 – PWM4_out
100 = PWM3 – PWM3_out
011 = PWM2 – PWM2_out
010 = PWM1 – PWM1_out
001 = Comparator C2– C2OUT_async
000 = Comparator C1 – C1OUT_async

TABLE 28-3: ENHANCED MID-RANGE INSTRUCTION SET (CONTINUED)

Mnemonic, Operands		Description	Cycles	14-Bit Opcode MSb			LSb	Status Affected	Notes
CONTROL OPERATIONS									
BRA	k	Relative Branch	2	11	001k	kkkk	kkkk		
BRW	–	Relative Branch with W	2	00	0000	0000	1011		
CALL	k	Call Subroutine	2	10	0kkk	kkkk	kkkk		
CALLW	–	Call Subroutine with W	2	00	0000	0000	1010		
GOTO	k	Go to address	2	10	1kkk	kkkk	kkkk		
RETFIE	k	Return from interrupt	2	00	0000	0000	1001		
RETLW	k	Return with literal in W	2	11	0100	kkkk	kkkk		
RETURN	–	Return from Subroutine	2	00	0000	0000	1000		
INHERENT OPERATIONS									
CLRWDT	–	Clear Watchdog Timer	1	00	0000	0110	0100	$\overline{TO}$, $\overline{PD}$	
NOP	–	No Operation	1	00	0000	0000	0000		
OPTION	–	Load OPTION_REG register with W	1	00	0000	0110	0010		
RESET	–	Software device Reset	1	00	0000	0000	0001		
SLEEP	–	Go into Standby mode	1	00	0000	0110	0011	$\overline{TO}$, $\overline{PD}$	
TRIS	f	Load TRIS register with W	1	00	0000	0110	0fff		
C-COMPILER OPTIMIZED									
ADDFSR	n, k	Add Literal k to FSRn	1	11	0001	0nkk	kkkk		
MOVIW	n mm	Move Indirect FSRn to W with pre/post inc/dec modifier, mm	1	00	0000	0001	0nmm kkkk	Z	**2, 3**
	k[n]	Move INDFn to W, Indexed Indirect.	1	11	1111	0nkk	1nmm	Z	**2**
MOVWI	n mm	Move W to Indirect FSRn with pre/post inc/dec modifier, mm	1	00	0000	0001	kkkk		**2, 3**
	k[n]	Move W to INDFn, Indexed Indirect.	1	11	1111	1nkk			**2**

Note 1: If the Program Counter (PC) is modified, or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

2: If this instruction addresses an INDF register and the MSb of the corresponding FSR is set, this instruction will require one additional instruction cycle.

3: See Table in the MOVIW and MOVWI instruction descriptions.

DECFSZ **Decrement f, Skip if 0**

Syntax:	[*label*] DECFSZ f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f) - 1 → (destination); skip if result = 0
Status Affected:	None
Description:	The contents of register 'f' are decremented. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'. If the result is '1', the next instruction is executed. If the result is '0', then a NOP is executed instead, making it a 2-cycle instruction.

INCFSZ **Increment f, Skip if 0**

Syntax:	[*label*] INCFSZ f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f) + 1 → (destination), skip if result = 0
Status Affected:	None
Description:	The contents of register 'f' are incremented. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'. If the result is '1', the next instruction is executed. If the result is '0', a NOP is executed instead, making it a 2-cycle instruction.

GOTO **Unconditional Branch**

Syntax:	[*label*] GOTO k
Operands:	$0 \le k \le 2047$
Operation:	k → PC<10:0> PCLATH<6:3> → PC<14:11>
Status Affected:	None
Description:	GOTO is an unconditional branch. The 11-bit immediate value is loaded into PC bits <10:0>. The upper bits of PC are loaded from PCLATH<4:3>. GOTO is a 2-cycle instruction.

IORLW **Inclusive OR literal with W**

Syntax:	[*label*] IORLW k
Operands:	$0 \le k \le 255$
Operation:	(W) .OR. k → (W)
Status Affected:	Z
Description:	The contents of the W register are OR'ed with the 8-bit literal 'k'. The result is placed in the W register.

INCF **Increment f**

Syntax:	[*label*] INCF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f) + 1 → (destination)
Status Affected:	Z
Description:	The contents of register 'f' are incremented. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.

IORWF **Inclusive OR W with f**

Syntax:	[*label*] IORWF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(W) .OR. (f) → (destination)
Status Affected:	Z
Description:	Inclusive OR the W register with register 'f'. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.

29.2 Standard Operating Conditions

The standard operating conditions for any device are defined as:

Operating Voltage: $V_{DDMIN} \le V_{DD} \le V_{DDMAX}$
Operating Temperature: $T_{A\_MIN} \le T_A \le T_{A\_MAX}$

V_{DD} — Operating Supply Voltage(1)

PIC16LF1508/9

V_{DDMIN} (Fosc ≤ 16 MHz) ..... +1.8V
V_{DDMIN} (16 MHz < Fosc ≤ 20 MHz) ..... +2.5V
V_{DDMAX} ..... +3.6V

PIC16F1508/9

V_{DDMIN} (Fosc ≤ 16 MHz) ..... +2.3V
V_{DDMIN} (16 MHz < Fosc ≤ 20 MHz) ..... +2.5V
V_{DDMAX} ..... +5.5V

T_A — Operating Ambient Temperature Range

Industrial Temperature

T_{A_MIN} ..... -40°C
T_{A_MAX} ..... +85°C

Extended Temperature

T_{A_MIN} ..... -40°C
T_{A_MAX} ..... +125°C

Note 1: See Parameter D001, DC Characteristics: Supply Voltage.

29.4 AC Characteristics

Timing Parameter Symbology has been created with one of the following formats:

1. TppS2ppS
2. TppS

T			
F	Frequency	T	Time

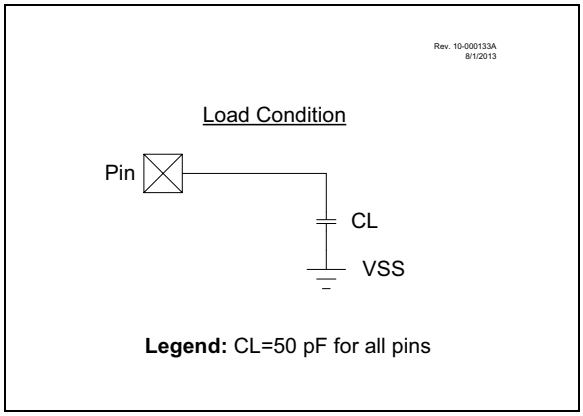
Lowercase letters (pp) and their meanings:

pp			
cc	CCP1	osc	CLKIN
ck	CLKOUT	rd	$\overline{RD}$
cs	$\overline{CS}$	rw	$\overline{RD}$ or $\overline{WR}$
di	SDIx	sc	SCKx
do	SDO	ss	$\overline{SS}$
dt	Data in	t0	T0CKI
io	I/O PORT	t1	T1CKI
mc	$\overline{MCLR}$	wr	$\overline{WR}$

Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (High-impedance)	V	Valid
L	Low	Z	High-impedance

FIGURE 29-4: LOAD CONDITIONS



Legend: CL=50 pF for all pins

TABLE 29-19: SPI MODE REQUIREMENTS

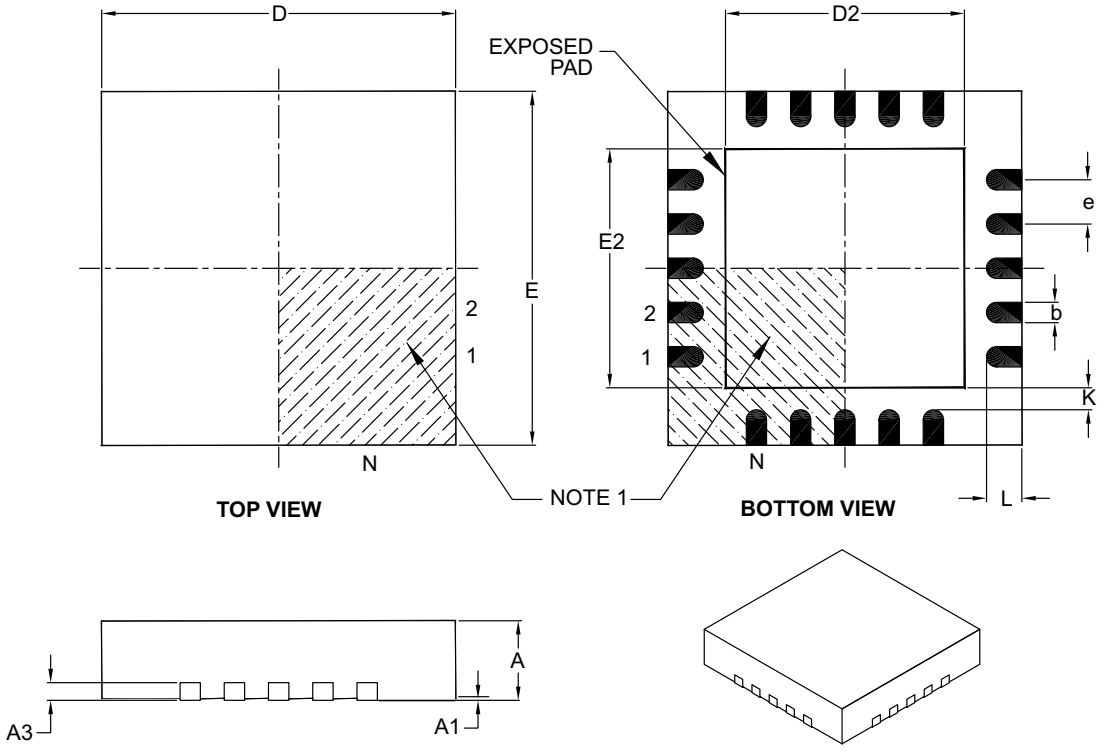
Standard Operating Conditions (unless otherwise stated)							
Param. No.	**Symbol**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
SP70*	TssL2scH, TssL2scL	$\overline{SS}\downarrow$ to SCK↓ or SCK↑ input	2.25 Tcy	—	—	ns	
SP71*	TscH	SCK input high time (Slave mode)	1 Tcy + 20	—	—	ns	
SP72*	TscL	SCK input low time (Slave mode)	1 Tcy + 20	—	—	ns	
SP73*	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge	100	—	—	ns	
SP74*	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge	100	—	—	ns	
SP75*	TdoR	SDO data output rise time	—	10	25	ns	3.0V ≤ VDD ≤ 5.5V
			—	25	50	ns	1.8V ≤ VDD ≤ 5.5V
SP76*	TdoF	SDO data output fall time	—	10	25	ns	
SP77*	TssH2doZ	$\overline{SS}\uparrow$ to SDO output high-impedance	10	—	50	ns	
SP78*	TscR	SCK output rise time (Master mode)	—	10	25	ns	3.0V ≤ VDD ≤ 5.5V
			—	25	50	ns	1.8V ≤ VDD ≤ 5.5V
SP79*	TscF	SCK output fall time (Master mode)	—	10	25	ns	
SP80*	TscH2doV, TscL2doV	SDO data output valid after SCK edge	—	—	50	ns	3.0V ≤ VDD ≤ 5.5V
			—	—	145	ns	1.8V ≤ VDD ≤ 5.5V
SP81*	TdoV2scH, TdoV2scL	SDO data output setup to SCK edge	1 Tcy	—	—	ns	
SP82*	TssL2doV	SDO data output valid after $\overline{SS}\downarrow$ edge	—	—	50	ns	
SP83*	TscH2ssH, TscL2ssH	$\overline{SS}\uparrow$ after SCK edge	1.5 Tcy + 40	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

20-Lead Plastic Quad Flat, No Lead Package (ML) – 4x4x0.9 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		20	
Pitch	e		0.50 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		4.00 BSC	
Exposed Pad Width	E2	2.60	2.70	2.80
Overall Length	D		4.00 BSC	
Exposed Pad Length	D2	2.60	2.70	2.80
Contact Width	b	0.18	0.25	0.30
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	–	–

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-126B

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